

Rev.F May.-2016



WR0596 M M E $\approx g^{\sim}$ || 1

Schottky Barrier Diode in a TO-263 Plastic Package.

$$H^* \rightarrow \mathbb{R} \cup \{H, \check{\alpha}, \check{\omega}, \infty\}$$

Low forward voltage drop, low power losses, High efficiency operation.

[illegible]

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and re

Parameter	Symbol	Rating	Unit
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IFSM

8.3ms Single Half Sine Wave Jedec Method

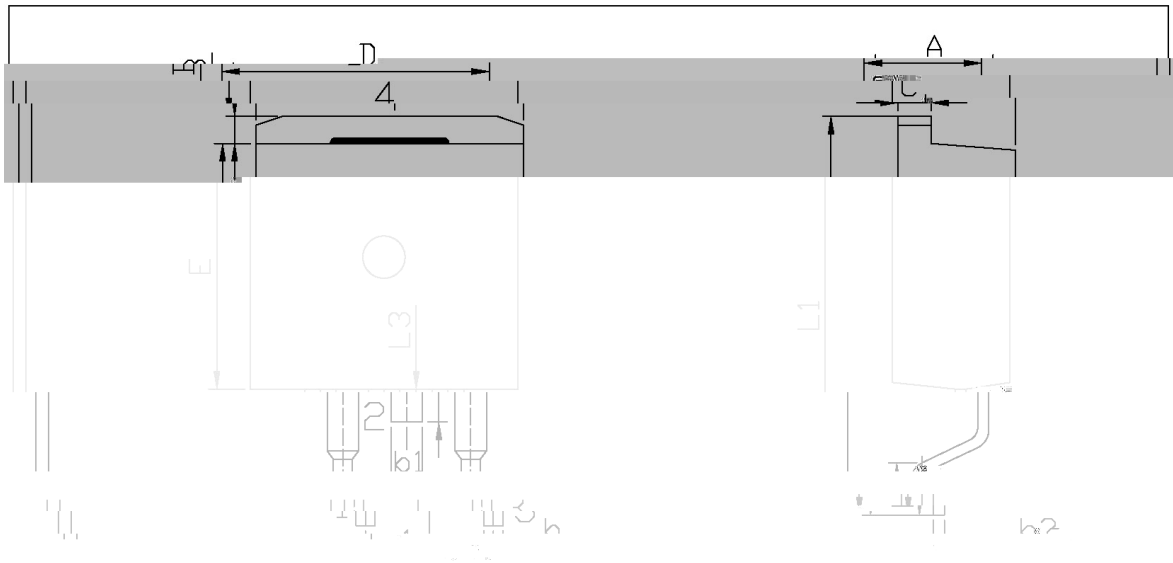
PEAK FORWARD SURGE CURRENT - (A)

NO. OF CYCLES AT 60HZ

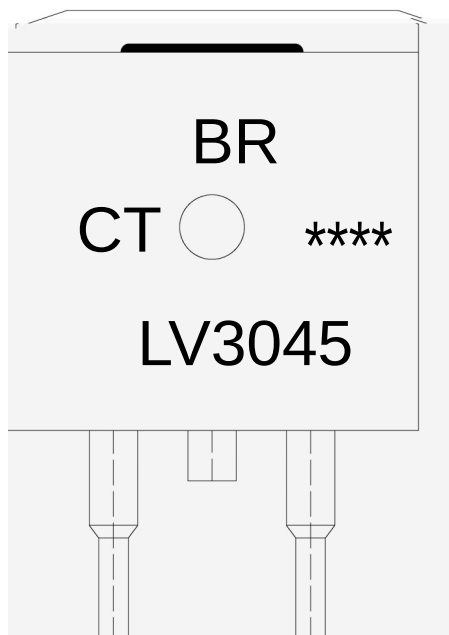
NO. OF CYCLES AT 60HZ	PEAK FORWARD SURGE CURRENT - (A)
0	250
10	210
20	180
30	160
40	145
50	130
60	118
70	108
80	98
90	88
100	75

[illegible]

/ Package Dimensions



/ Marking Instructions



б " X

EU X

OY6378 X

FW:

---- X

Note:

BR:

OY6378 X

FW:

****:

BR

CT

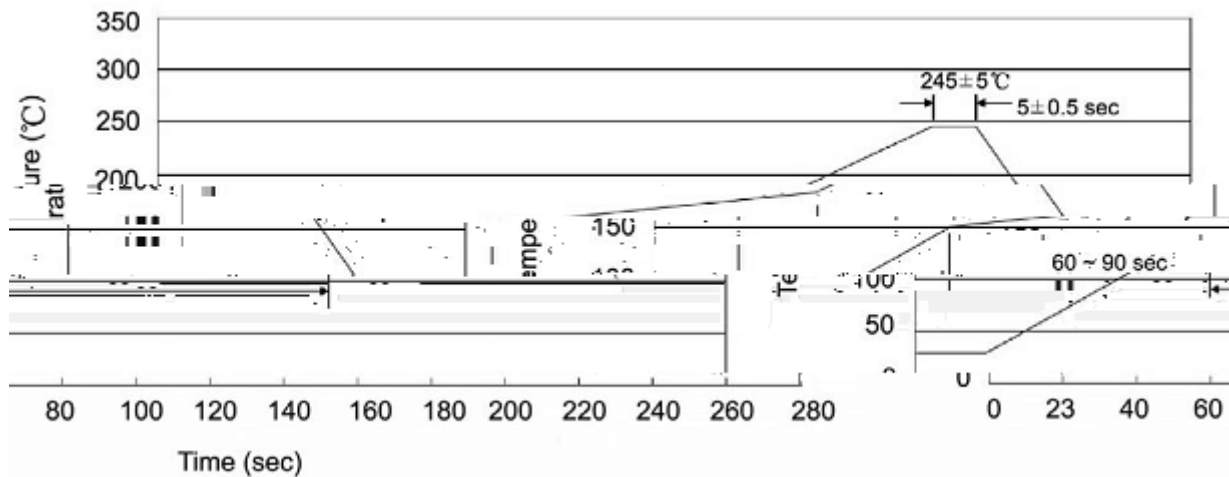
FW

Company Code

Product Type.

Internal Structure

Lot No. Code, code change with Lot No.


() / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明

1. 预加热: 25~150 °C, Time: 60~90sec;
2. 峰值温度: 245±5 °C, Time: 5±0.5sec;
3. 冷却速度: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 245±5 °C, Duration: 5±0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

测试条件: 260±5 °C, Time: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

/ Packaging SPEC.

包装规格 / REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 × 24	360×360×50	385×257×392